

N-channel 800 V, 0.55 Ω typ., 8 A MDmesh™ K5 Power MOSFET in a TO-220FP package

Datasheet - production data

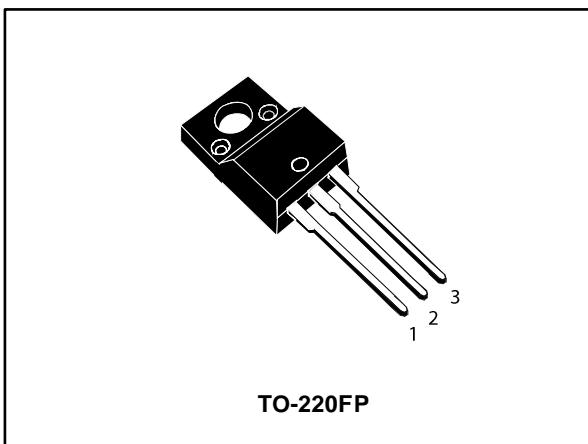
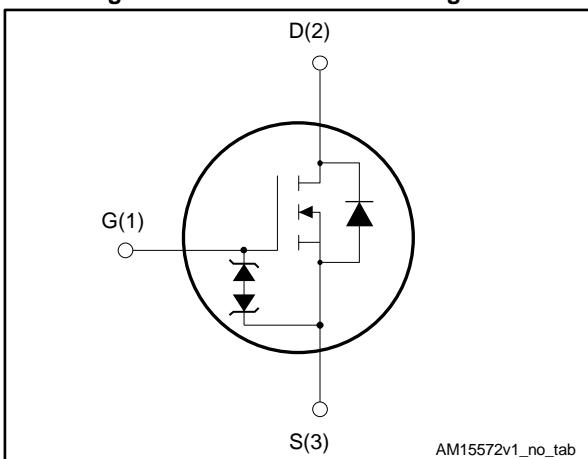


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D
STF10LN80K5	800 V	0.63 Ω	8 A

- Industry's lowest R_{DS(on)} x area
- Industry's best figure of merit (FoM)
- Ultra-low gate charge
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications

Description

This very high voltage N-channel Power MOSFET is designed using MDmesh™ K5 technology based on an innovative proprietary vertical structure. The result is a dramatic reduction in on-resistance and ultra-low gate charge for applications requiring superior power density and high efficiency.

Table 1: Device summary

Order code	Marking	Package	Packing
STF10LN80K5	10LN80K5	TO-220FP	Tube

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 30	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	8	A
$I_D^{(1)}$	Drain current (continuous) at $T_C = 100^\circ\text{C}$	5	A
$I_D^{(2)}$	Drain current pulsed	32	A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	25	W
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink ($t=1\text{s}; T_C=25^\circ\text{C}$)	2500	V
$dv/dt^{(3)}$	Peak diode recovery voltage slope	4.5	V/ns
$dv/dt^{(4)}$	MOSFET dv/dt ruggedness	50	
T_j	Operating junction temperature	- 55 to 150	$^\circ\text{C}$
T_{stg}	Storage temperature		

Notes:

(1) Limited by maximum junction temperature.

(2) Pulse width limited by safe operating area

(3) $I_{SD} \leq 8 \text{ A}, dI/dt \leq 100 \text{ A}/\mu\text{s}; V_{DS} \text{ peak} \leq V_{(BR)DSS}$ (4) $V_{DS} \leq 640 \text{ V}$

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	5	$^\circ\text{C}/\text{W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	62.5	$^\circ\text{C}/\text{W}$

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T_{jmax})	2.7	A
E_{AS}	Single pulse avalanche energy (starting $T_j = 25^\circ\text{C}, I_D = I_{AR}, V_{DD} = 50 \text{ V}$)	240	mJ

2 Electrical characteristics

$T_C = 25^\circ\text{C}$ unless otherwise specified

Table 5: On/off-state

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	800			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 800 \text{ V}$			1	μA
		$V_{GS} = 0 \text{ V}, V_{DS} = 800 \text{ V}$ $T_C = 125^\circ\text{C}$			50	μA
I_{GSS}	Gate body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 10	μA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 100 \mu\text{A}$	3	4	5	V
$R_{DS(\text{on})}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}$		0.55	0.63	Ω

Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz},$ $V_{GS} = 0 \text{ V}$	-	427	-	pF
C_{oss}	Output capacitance		-	43	-	pF
C_{rss}	Reverse transfer capacitance		-	0.25	-	pF
$C_{o(\text{tr})}^{(1)}$	Equivalent capacitance time related	$V_{DS} = 0 \text{ to } 640 \text{ V},$ $V_{GS} = 0 \text{ V}$	-	72	-	pF
$C_{o(er)}^{(2)}$	Equivalent capacitance energy related			27	-	pF
R_g	Intrinsic gate resistance	$f = 1 \text{ MHz}, I_D = 0 \text{ A}$	-	7	-	Ω
Q_g	Total gate charge	$V_{DD} = 640 \text{ V}, I_D = 8 \text{ A}$ $V_{GS} = 10 \text{ V}$ See Figure 16: "Test circuit for gate charge behavior"	-	15	-	nC
Q_{gs}	Gate-source charge		-	4.2	-	nC
Q_{gd}	Gate-drain charge		-	9	-	nC

Notes:

⁽¹⁾Time related is defined as a constant equivalent capacitance giving the same charging time as Coss when V_{DS} increases from 0 to 80% V_{DSS}

⁽²⁾Energy related is defined as a constant equivalent capacitance giving the same stored energy as Coss when V_{DS} increases from 0 to 80% V_{DSS}

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 400 \text{ V}, I_D = 4 \text{ A}, R_G = 4.7 \Omega$ $V_{GS} = 10 \text{ V}$ See Figure 15: "Test circuit for resistive load switching times" and Figure 20: "Switching time waveform"	-	11.8	-	ns
t_r	Rise time		-	10	-	ns
$t_{d(off)}$	Turn-off delay time		-	28	-	ns
t_f	Fall time		-	13	-	ns

Table 8: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		8	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		32	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 8 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.5	V
t_{rr}	Reverse recovery time	$I_{SD} = 8 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s},$	-	350		ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 60 \text{ V}$, see Figure 17: "Test circuit for inductive load switching and diode recovery times"	-	3.9		μC
I_{RRM}	Reverse recovery current	$V_{DD} = 60 \text{ V}, T_j = 150^\circ\text{C}$, see Figure 17: "Test circuit for inductive load switching and diode recovery times"	-	22.5		A
t_{rr}	Reverse recovery time	$I_{SD} = 8 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s},$	-	505		ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 60 \text{ V}, T_j = 150^\circ\text{C}$, see Figure 17: "Test circuit for inductive load switching and diode recovery times"	-	5		μC
I_{RRM}	Reverse recovery current	$V_{DD} = 60 \text{ V}, T_j = 150^\circ\text{C}$, see Figure 17: "Test circuit for inductive load switching and diode recovery times"	-	20		A

Notes:

(1) Pulse width limited by safe operating area

(2) Pulsed: pulse duration = 300 μs , duty cycle 1.5%

Table 9: Gate-source Zener diode

Symbol	Parameter	Test conditions	Min	Typ.	Max	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	$I_{GS} = \pm 1 \text{ mA}, I_D = 0 \text{ A}$	30	-	-	V

The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.

2.2 Electrical characteristics (curves)

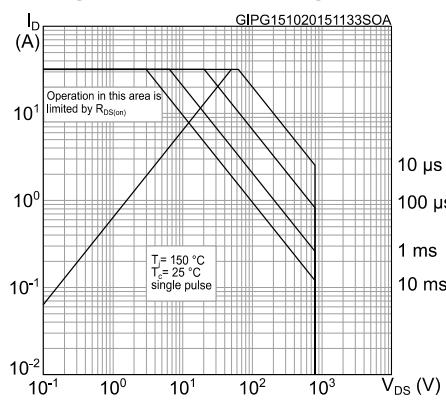
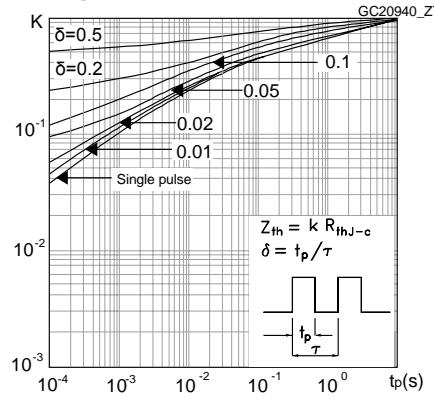
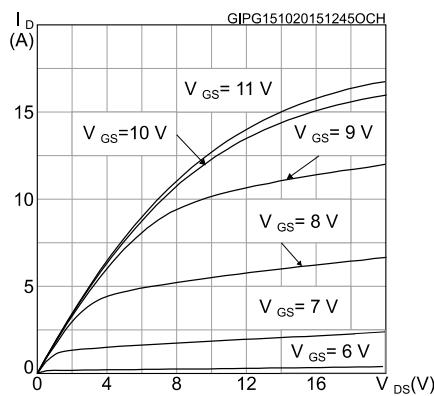
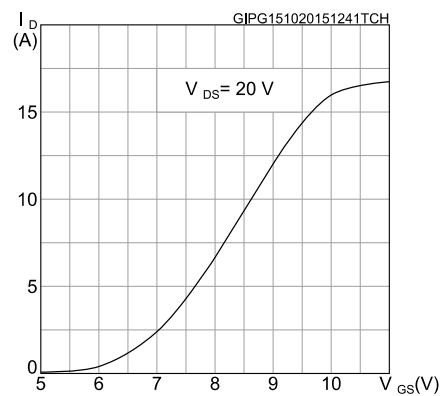
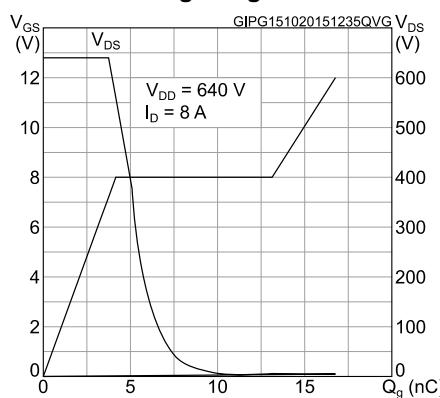
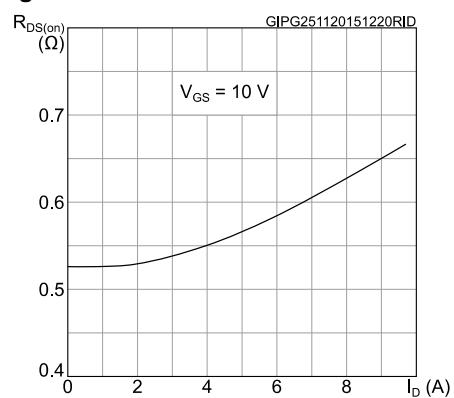
Figure 2: Safe operating area**Figure 3: Thermal impedance****Figure 4: Output characteristics****Figure 5: Transfer characteristics****Figure 6: Gate charge vs gate-source voltage****Figure 7: Static drain-source on-resistance**

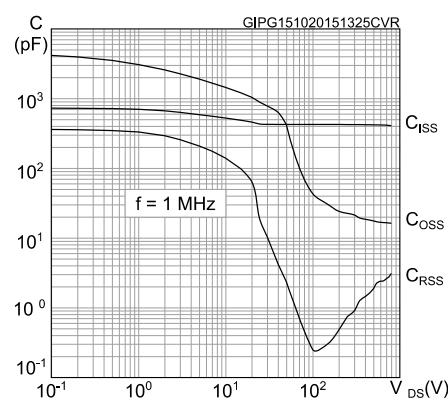
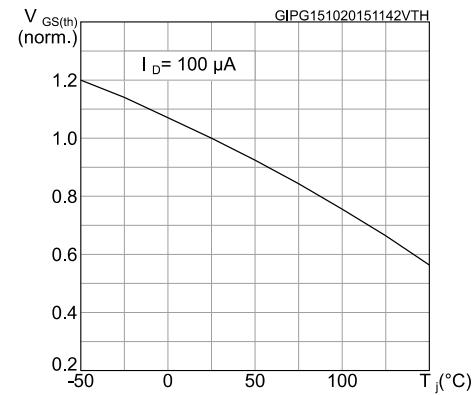
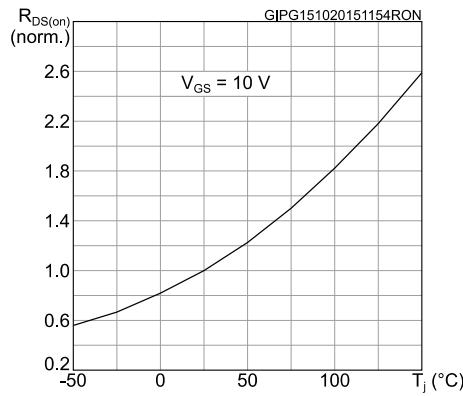
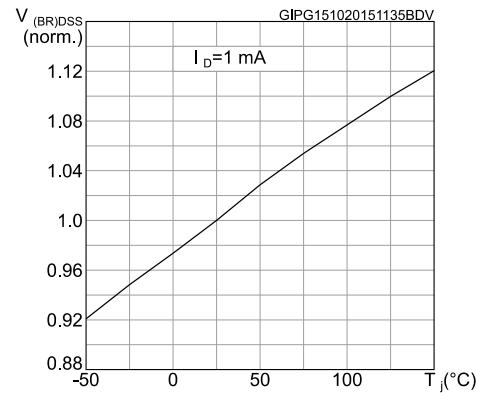
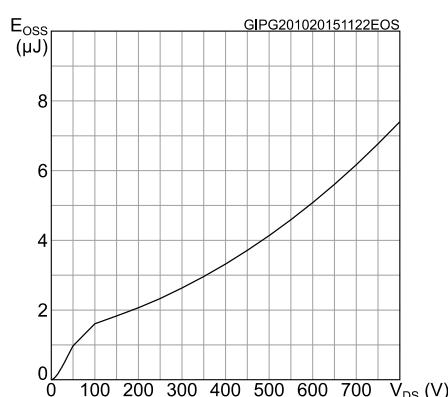
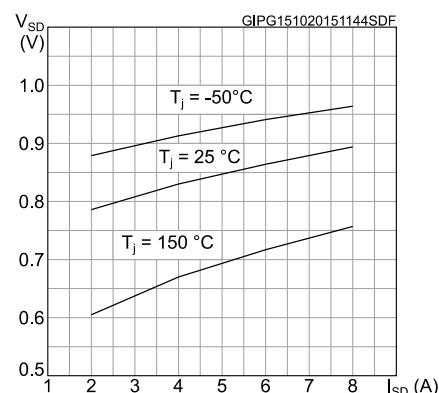
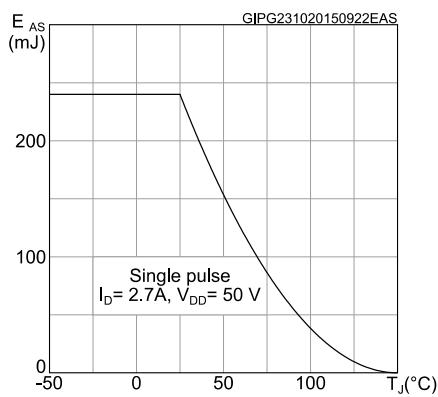
Figure 8: Capacitance variations**Figure 9: Normalized gate threshold voltage vs temperature****Figure 10: Normalized on-resistance vs temperature****Figure 11: Normalized $V_{(BR)DSS}$ vs temperature****Figure 12: Output capacitance stored energy****Figure 13: Source-drain diode forward characteristics**

Figure 14: Maximum avalanche energy vs starting T_J 

3 Test circuits

Figure 15: Test circuit for resistive load switching times

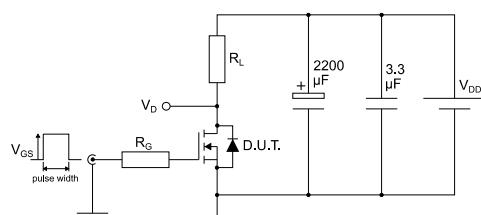


Figure 16: Test circuit for gate charge behavior

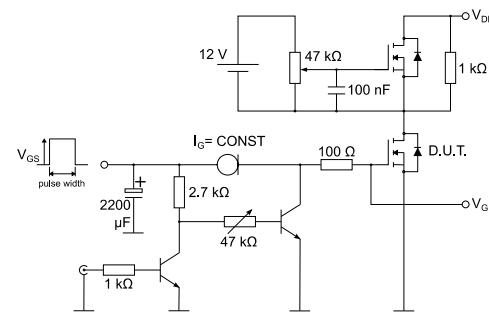


Figure 17: Test circuit for inductive load switching and diode recovery times

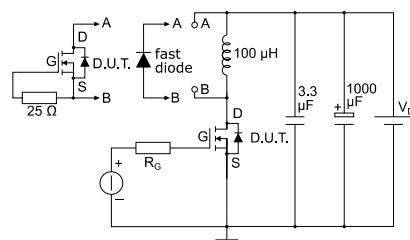


Figure 18: Unclamped inductive load test circuit

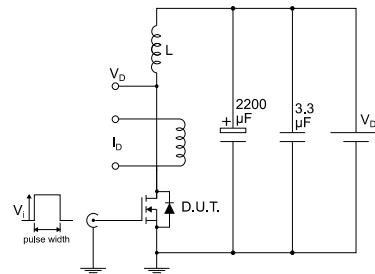


Figure 19: Unclamped inductive waveform

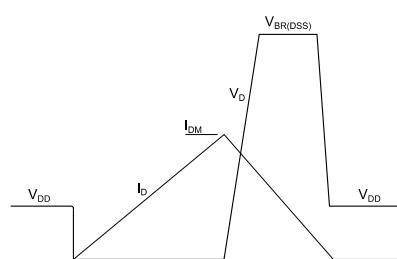
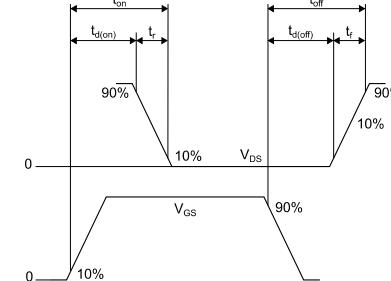


Figure 20: Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
ECOPACK® is an ST trademark.

4.1 TO-220FP package information

Figure 21: TO-220FP package outline

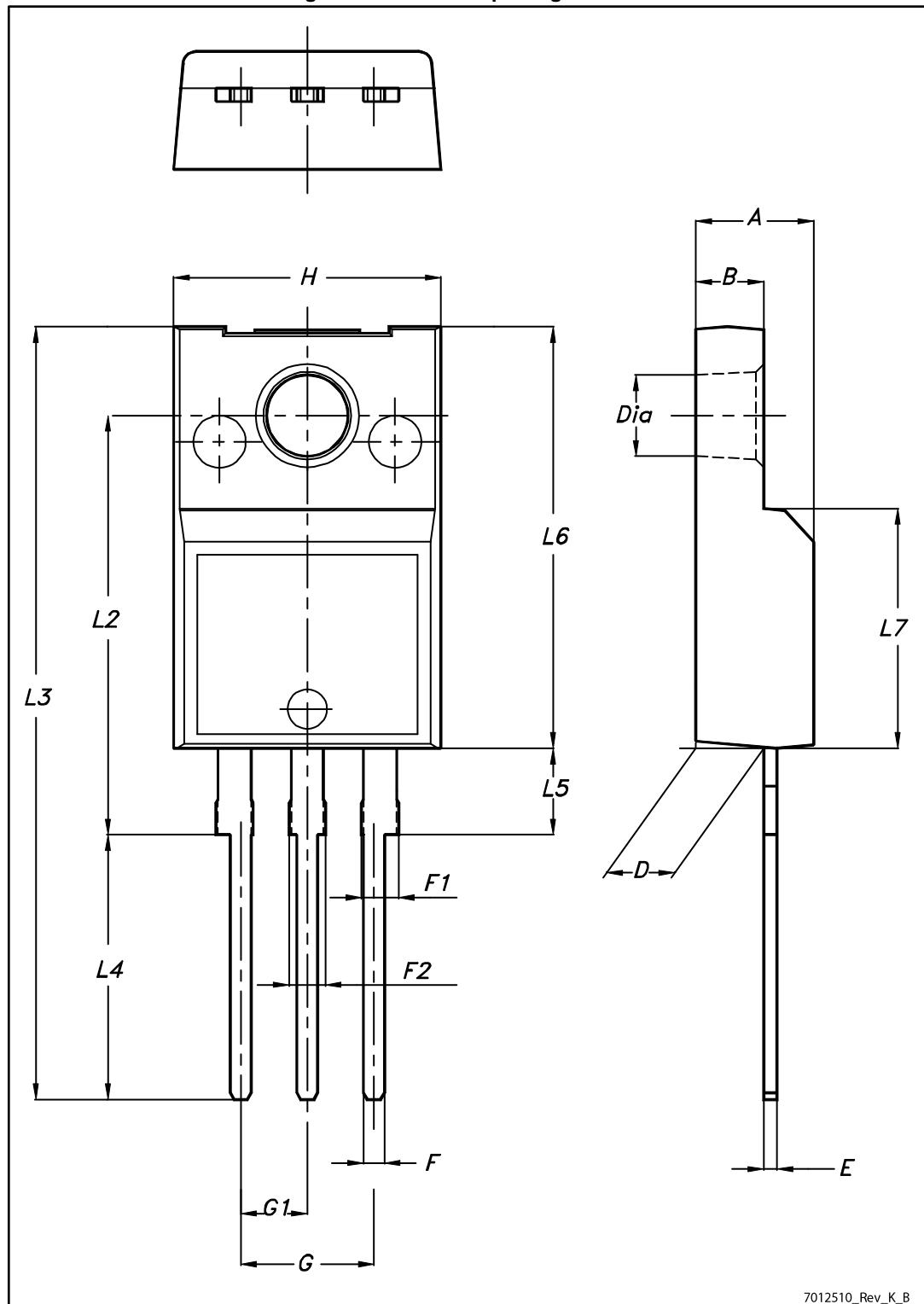


Table 10: TO-220FP package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

5 Revision history

Table 11: Document revision history

Date	Revision	Changes
26-May-2015	1	First release.
21-Oct-2015	2	Modified: $R_{DS(on)}$ value in cover page. Modified: Table 2: "Absolute maximum ratings", Table 4: "Avalanche characteristics", Table 5: "On/off-state", Table 6: "Dynamic", Table 7: "Switching times", Table 8: "Source-drain diode". Added: Section 3.1: "Electrical characteristics (curves)". Minor text changes.
01-Dec-2015	3	Modified: Table 2: "Absolute maximum ratings" , and Table 3: "Thermal data" .

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